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To the Honorable Commissioner c  
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## 1. Name of conveying party(ies):

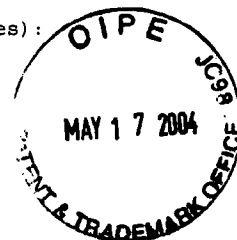
Daisuke IMANARI  
Masayasu OKUDA  
Naohika KOGURE  
Masato NAITO

S.17-04

## 2. Name and address of receiving party(ies):

Name: JSP Corporation

Internal Address:



Additional name(s) of conveying party(ies)  
attached? ☐ Yes ☐ No

## 3. Nature of Conveyance

- ☐ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Other \_\_\_\_\_

Street Address: 4-2, Marunouchi 3-chomeChiyoda-kuCity: Tokyo State: Japan ZIP: 100-0005Execution Date: February 9, 2004Additional name(s) & address(es) attached? ☐ Yes ☐ No

## 4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date  
of the application is:

## A. Patent Application No.(s)

10/782,941

## B. Patent No.(s)

Additional numbers attached? ☐ Yes ☐ No5. Name and address of party to whom  
correspondence concerning document  
should be mailed:Name: SHERMAN & SHALLOWAY

Internal Address: \_\_\_\_\_

Street Address: \_\_\_\_\_

413 North Washington StreetCity: Alexandria State: VAZIP: 223146. Total number of applications and patents  
involved:..... [ 1 ]7. Total fee (37 CFR 3.41).....\$40.00☐ Enclosed☐ Authorized to be charged to deposit account

## 8. Deposit account number:

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## 9. Statement and signature.

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attached copy is a true copy of the original document

Robert L. Haines

Name of Person Signing

  
SignatureMay 13, 2004

Date

Total number of pages including cover sheet, attachments, and document [ 2 ]

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## ASSIGNMENT

WHEREAS, We, Daisuke Imanari, Masayasu Okuda, Naochika Kogure, Masato Naito, residing respectively at c/o KANUMA RESEARCH CENTER OF JSP CORPORATION, 10-3, SATSUKI-CHO, KANUMA-SHI, TOCHIGI 322-0014, JAPAN; c/o KANUMA RESEARCH CENTER OF JSP CORPORATION, 10-3, SATSUKI-CHO, KANUMA-SHI, TOCHIGI 322-0014, JAPAN; c/o KANUMA RESEARCH CENTER OF JSP CORPORATION, 10-3, SATSUKI-CHO, KANUMA-SHI, TOCHIGI 322-0014, JAPAN; c/o KANUMA RESEARCH CENTER OF JSP CORPORATION, 10-3, SATSUKI-CHO, KANUMA-SHI, TOCHIGI 322-0014, JAPAN (hereinafter referred to as Inventors), have invented certain new and useful improvements in FOAM-MOLDED ARTICLE AND MANUFACTURING METHOD THEREOF; for which an application for United States Letters Patent was filed in the United States on N/A and assigned Serial Number N/A.

WHEREAS, JSP CORPORATION, a corporation of Japan, having a place of business at 4-2, Marunouchi 3-chome, Chiyoda-ku, Tokyo 100-0005, Japan (hereinafter referred to as Company), is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States and in any and all foreign countries.

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to us in hand paid, the receipt whereof is hereby acknowledged, and other valuable considerations, the said Inventors have sold, assigned and transferred, and by the presents do sell, assign and transfer unto said Company, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries and the entire right, title and interest in and to any and all Letters Patent, which may be granted thereof in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations and extensions thereof.

We hereby authorize and request the Patent Office Officials in the United States and in any and all foreign countries to issue any and all of said Letters Patent, when granted, to said Company as the assignee of the entire right, title and interest in and to the same, for the sole use and behalf of the said Company, its successors and assigns.

FURTHER, We agree that we will communicate to said Company or its representatives any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, substitution, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said Company, make all rightful oaths and generally do everything possible to aid said Company, its successors and assigns, to obtain and enforce proper protection for said invention in the United States and in any and all foreign countries.

IN TESTIMONY WHEREOF, We have hereunto set our hands this 9th day of February, 2004.

Signed in the presence of:

Witness: Atsuo Shimizu  
Atsuo Shimizu

Signed: Daisuke Imanari  
Daisuke Imanari

Witness: Atsuo Shimizu  
Atsuo Shimizu

Signed: Masayasu Okuda  
Masayasu Okuda

Witness: Atsuo Shimizu  
Atsuo Shimizu

Signed: Naochika Kogure  
Naochika Kogure

Witness: Atsuo Shimizu  
Atsuo Shimizu

Signed: Masato Naito  
Masato Naito

PATENT

RECORDED: 05/17/2004

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